

1367645-4 ✓ ACTIVE



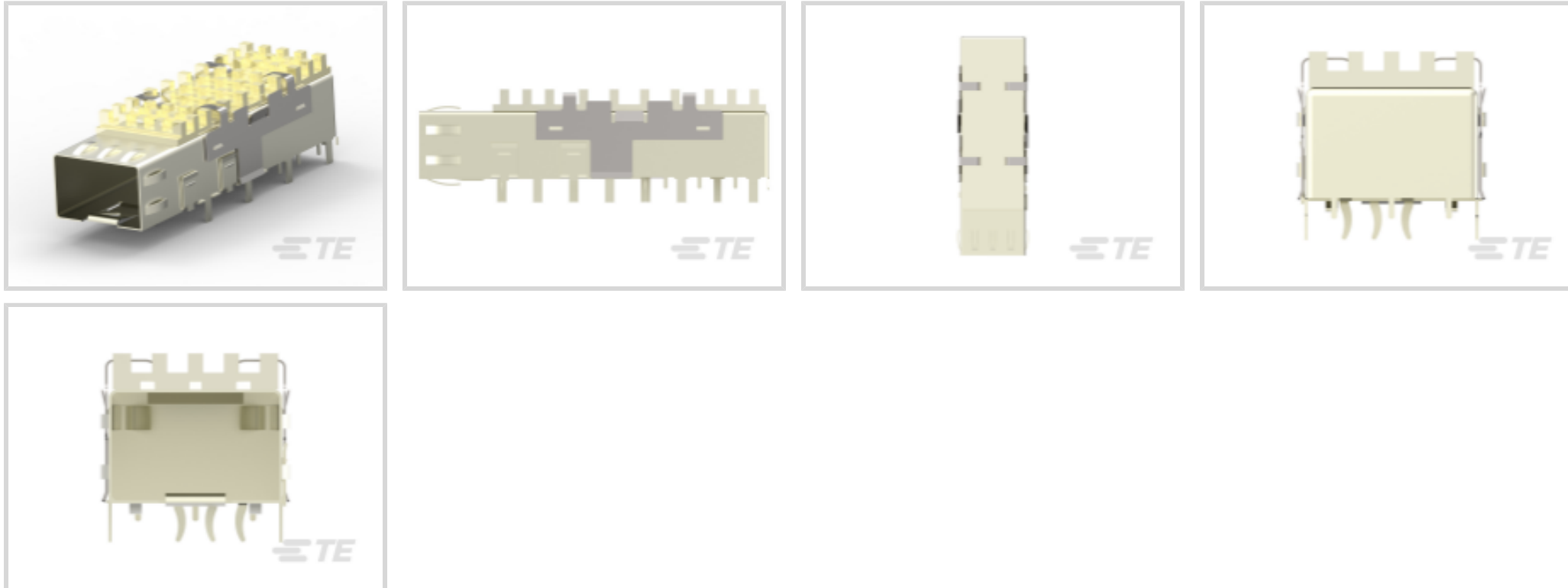
SFP28 | DWDM

TE Internal #: 1367645-4

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 4 Gb/s,  
Internal/External EMI Springs, SFP, Not Optional, 1 x 1, Through  
Hole - Press-Fit, DWDM

[View on TE.com >](#)

Connectors > Pluggable IO Connectors & Cages > SFP, SFP+ & zSFP+ > SFP Connectors



Pluggable I/O Product Type: **Cage Assembly**

Data Rate (Max): **4 Gb/s**

EMI Containment Feature Type: **Internal/External EMI Springs**

Pluggable I/O Applications: **SFP**

Lightpipe Options: **Not Optional**

[All SFP Connectors \(10\)](#)

## Features

### Product Type Features

Form Factor	SFP
Cage Type	Single
Thermal Accessory Type Included	Heat Sink
Pluggable I/O Product Type	Cage Assembly
Lightpipe Options	Not Optional
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

### Configuration Features

Port Matrix Configuration	1 x 1
Number of Ports	1

### Electrical Characteristics



Data Rate (Max)	4 Gb/s
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### Body Features

Heat Sink Height Class	PCI
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Heat Sink Height	4.2 mm[.165 in]
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Heat Sink Style	Pin
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### Termination Features

Termination Post & Tail Length	3 mm[.118 in]
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Termination Method to Printed Circuit Board	Through Hole - Press-Fit
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### Mechanical Attachment

Connector Mounting Type	Board Mount
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### Housing Features

Cage Material	Copper Alloy
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### Dimensions

PCB Thickness (Recommended)	2.25 mm[.089 in]
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### Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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### Operation/Application

Heat Sink Compatible	Yes
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For Use With Pluggable I/O Products	SFP SMT Connector
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Pluggable I/O Applications	SFP
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Circuit Application	Signal
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### Packaging Features

Packaging Method	Box & Tray
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### Other

EMI Containment Feature Type	Internal/External EMI Springs
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### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JUNE 2023 (235)

Candidate List Declared Against: JUNE 2023 (235)

Does not contain REACH SVHC

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

### Compatible Parts



TE Part # CAT-SF59-C76264  
SFP Connectors



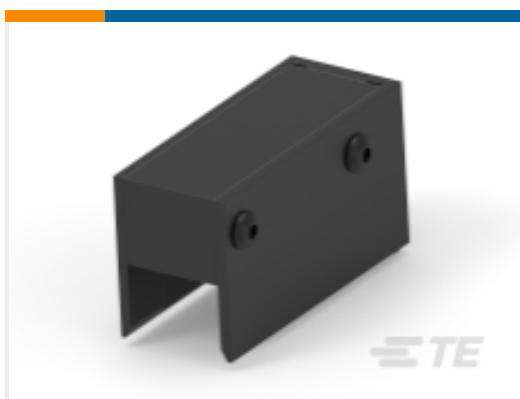
TE Part # 1367147-1  
SFP COVER, UNPLATED



TE Part # 1367147-3  
SFP COVER, UNPL, NO LOGO

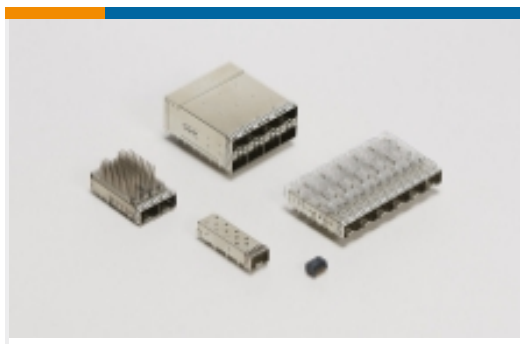


TE Part # 1761394-1  
DUST COVER, SFP, GANGED & STACKED



TE Part # 2215084-4  
ASSY, SEATING TOOL, SFP 1X1

Also in the Series | DWDM



SFP, SFP+ & zSFP+(4)

## Customers Also Bought



TE Part #2007637-8  
SFP+ assy 2x2 Spring Fingers N



TE Part #3-640426-3  
03P MTA156 CONN ASSY 18AWG  
ORA



TE Part #3-640599-6  
06P MTA156 CONN ASSY 18AWG  
ORA



TE Part #1658621-9  
40 NOVO MIL/CTR 15DP, LEAD FREE  
ORA



TE Part #2170704-4  
CAGE ASSY, QSFP28 1X1, SPRING, HS



TE Part #1367147-1  
SFP COVER, UNPLATED



TE Part #NB18994001  
RNF-100-1/4-CL-SP

## Documents

### Product Drawings

[DWDM Kit Assy, PCI \(4.2\)](#)

English

### CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_1367645-4\\_A.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1367645-4\\_A.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1367645-4\\_A.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.



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**Product Specifications**

**Product Specification**

English